

## ABSTRACT OF THE DISCLOSURE

A semiconductor wafer or other bulk semiconductor substrate having a plurality of dice thereon is manufactured using conventional processing techniques. The wafer is subjected to testing to identify functional and nonfunctional dice. The locations of the functional dice are analyzed to determine the location of immediately adjacent or closely proximate functional dice. A group of functional dice is identified and an interconnection circuit is formed therebetween. The functional die group, once interconnected, is then segmented from the wafer while maintaining the unitary integrity of the functional die group as well as the associated interconnections between dice. Modules including one or more functional die groups and methods of fabricating functional die groups and modules are also disclosed.

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